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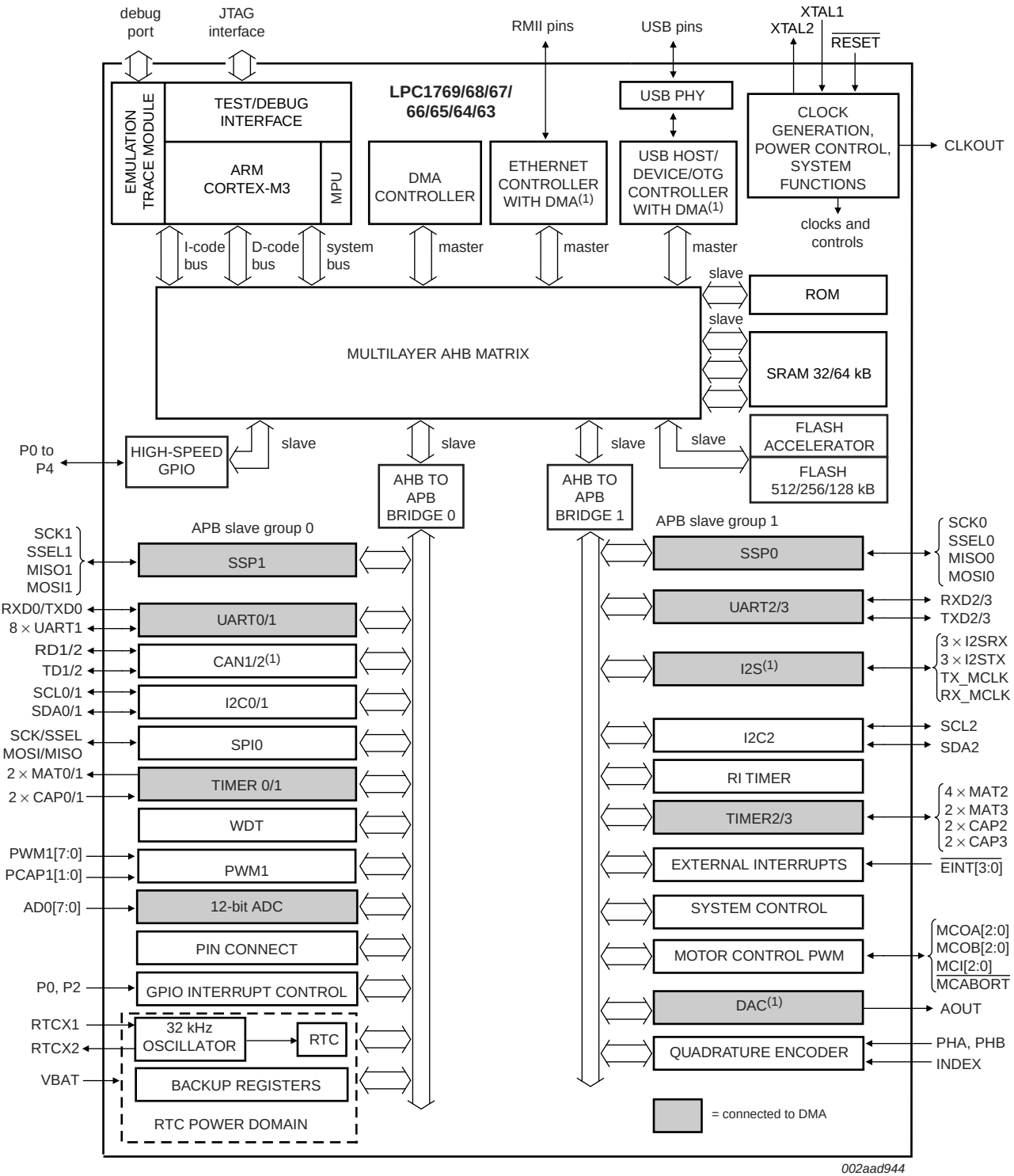
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	CANbus, I²C, IrDA, Microwire, SPI, SSI, SSP, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	70
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	A/D 8x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFBGA
Supplier Device Package	100-TFBGA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1765fet100-551

6. Block diagram



(1) Not available on all parts. See Table 2.

Fig 1. Block diagram

Table 5. Pin description *…continued*

Symbol	Pin/ball				Type	Description
	LQFP100	TFBGA100	WLCSP100			
P0[4]/ I2SRX_CLK/ RD2/CAP2[0]	81	A8	G2	[1]	I/O	**P0[4] —** General purpose digital input/output pin.
					I/O	**I2SRX_CLK —** Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the *I²S-bus specification*. (LPC1769/68/67/66/65/63 only).
					I	**RD2 —** CAN2 receiver input. (LPC1769/68/66/65/64 only).
					I	**CAP2[0] —** Capture input for Timer 2, channel 0.
P0[5]/ I2SRX_WS/ TD2/CAP2[1]	80	D7	H1	[1]	I/O	**P0[5] —** General purpose digital input/output pin.
					I/O	**I2SRX_WS —** Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*. (LPC1769/68/67/66/65/63 only).
					O	**TD2 —** CAN2 transmitter output. (LPC1769/68/66/65/64 only).
					I	**CAP2[1] —** Capture input for Timer 2, channel 1.
P0[6]/ I2SRX_SDA/ SSEL1/MAT2[0]	79	B8	G3	[1]	I/O	**P0[6] —** General purpose digital input/output pin.
					I/O	**I2SRX_SDA —** Receive data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I²S-bus specification*. (LPC1769/68/67/66/65/63 only).
					I/O	**SSEL1 —** Slave Select for SSP1.
					O	**MAT2[0] —** Match output for Timer 2, channel 0.
P0[7]/ I2STX_CLK/ SCK1/MAT2[1]	78	A9	J1	[1]	I/O	**P0[7] —** General purpose digital input/output pin.
					I/O	**I2STX_CLK —** Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the *I²S-bus specification*. (LPC1769/68/67/66/65/63 only).
					I/O	**SCK1 —** Serial Clock for SSP1.
					O	**MAT2[1] —** Match output for Timer 2, channel 1.
P0[8]/ I2STX_WS/ MISO1/MAT2[2]	77	C8	H2	[1]	I/O	**P0[8] —** General purpose digital input/output pin.
					I/O	**I2STX_WS —** Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*. (LPC1769/68/67/66/65/63 only).
					I/O	**MISO1 —** Master In Slave Out for SSP1.
					O	**MAT2[2] —** Match output for Timer 2, channel 2.
P0[9]/ I2STX_SDA/ MOSI1/MAT2[3]	76	A10	H3	[1]	I/O	**P0[9] —** General purpose digital input/output pin.
					I/O	**I2STX_SDA —** Transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I²S-bus specification*. (LPC1769/68/67/66/65/63 only).
					I/O	**MOSI1 —** Master Out Slave In for SSP1.
					O	**MAT2[3] —** Match output for Timer 2, channel 3.
P0[10]/TXD2/ SDA2/MAT3[0]	48	H7	H8	[1]	I/O	**P0[10] —** General purpose digital input/output pin.
					O	**TXD2 —** Transmitter output for UART2.
					I/O	**SDA2 —** I²C2 data input/output (this is not an open-drain pin).
					O	**MAT3[0] —** Match output for Timer 3, channel 0.

Table 5. Pin description *…continued*

Symbol	Pin/ball				Type	Description
	LQFP100	TFBGA100	WLCSP100			
P0[11]/RXD2/ SCL2/MAT3[1]	49	K9	J10	[1]	I/O	**P0[11] —** General purpose digital input/output pin.
					I	**RXD2 —** Receiver input for UART2.
					I/O	**SCL2 —** I^2C2 clock input/output (this is not an open-drain pin).
					O	**MAT3[1] —** Match output for Timer 3, channel 1.
P0[15]/TXD1/ SCK0/SCK	62	F10	H6	[1]	I/O	**P0[15] —** General purpose digital input/output pin.
					O	**TXD1 —** Transmitter output for UART1.
					I/O	**SCK0 —** Serial clock for SSP0.
					I/O	**SCK —** Serial clock for SPI.
P0[16]/RXD1/ SSEL0/SSEL	63	F8	J5	[1]	I/O	**P0[16] —** General purpose digital input/output pin.
					I	**RXD1 —** Receiver input for UART1.
					I/O	**SSEL0 —** Slave Select for SSP0.
					I/O	**SSEL —** Slave Select for SPI.
P0[17]/CTS1/ MISO0/MISO	61	F9	K6	[1]	I/O	**P0[17] —** General purpose digital input/output pin.
					I	**CTS1 —** Clear to Send input for UART1.
					I/O	**MISO0 —** Master In Slave Out for SSP0.
					I/O	**MISO —** Master In Slave Out for SPI.
P0[18]/DCD1/ MOSI0/MOSI	60	F6	J6	[1]	I/O	**P0[18] —** General purpose digital input/output pin.
					I	**DCD1 —** Data Carrier Detect input for UART1.
					I/O	**MOSI0 —** Master Out Slave In for SSP0.
					I/O	**MOSI —** Master Out Slave In for SPI.
P0[19]/DSR1/ SDA1	59	G10	K7	[1]	I/O	**P0[19] —** General purpose digital input/output pin.
					I	**DSR1 —** Data Set Ready input for UART1.
					I/O	**SDA1 —** I^2C1 data input/output (this is not an I^2C-bus compliant open-drain pin).
P0[20]/DTR1/SCL1	58	G9	J7	[1]	I/O	**P0[20] —** General purpose digital input/output pin.
					O	**DTR1 —** Data Terminal Ready output for UART1. Can also be configured to be an RS-485/EIA-485 output enable signal.
					I/O	**SCL1 —** I^2C1 clock input/output (this is not an I^2C-bus compliant open-drain pin).
P0[21]/RI1/RD1	57	G8	H7	[1]	I/O	**P0[21] —** General purpose digital input/output pin.
					I	**RI1 —** Ring Indicator input for UART1.
					I	**RD1 —** CAN1 receiver input. (LPC1769/68/66/65/64 only).
P0[22]/RTS1/TD1	56	H10	K8	[1]	I/O	**P0[22] —** General purpose digital input/output pin.
					O	**RTS1 —** Request to Send output for UART1. Can also be configured to be an RS-485/EIA-485 output enable signal.
					O	**TD1 —** CAN1 transmitter output. (LPC1769/68/66/65/64 only).

Table 5. Pin description *…continued*

Symbol	Pin/ball				Type	Description
	LQFP100	TFBGA100	WLCSP100			
P1[0] to P1[31]					I/O	**Port 1:** Port 1 is a 32-bit I/O port with individual direction controls for each bit. The operation of port 1 pins depends upon the pin function selected via the pin connect block. Pins 2, 3, 5, 6, 7, 11, 12, and 13 of this port are not available.
P1[0]/ ENET_TXD0	95	D5	C1	[1]	I/O	**P1[0] —** General purpose digital input/output pin.
					O	**ENET_TXD0 —** Ethernet transmit data 0. (LPC1769/68/67/66/64 only).
P1[1]/ ENET_TXD1	94	B4	C2	[1]	I/O	**P1[1] —** General purpose digital input/output pin.
					O	**ENET_TXD1 —** Ethernet transmit data 1. (LPC1769/68/67/66/64 only).
P1[4]/ ENET_TX_EN	93	A4	D2	[1]	I/O	**P1[4] —** General purpose digital input/output pin.
					O	**ENET_TX_EN —** Ethernet transmit data enable. (LPC1769/68/67/66/64 only).
P1[8]/ ENET_CRS	92	C5	D1	[1]	I/O	**P1[8] —** General purpose digital input/output pin.
					I	**ENET_CRS —** Ethernet carrier sense. (LPC1769/68/67/66/64 only).
P1[9]/ ENET_RXD0	91	B5	D3	[1]	I/O	**P1[9] —** General purpose digital input/output pin.
					I	**ENET_RXD0 —** Ethernet receive data. (LPC1769/68/67/66/64 only).
P1[10]/ ENET_RXD1	90	A5	E3	[1]	I/O	**P1[10] —** General purpose digital input/output pin.
					I	**ENET_RXD1 —** Ethernet receive data. (LPC1769/68/67/66/64 only).
P1[14]/ ENET_RX_ER	89	D6	E2	[1]	I/O	**P1[14] —** General purpose digital input/output pin.
					I	**ENET_RX_ER —** Ethernet receive error. (LPC1769/68/67/66/64 only).
P1[15]/ ENET_REF_CLK	88	C6	E1	[1]	I/O	**P1[15] —** General purpose digital input/output pin.
					I	**ENET_REF_CLK —** Ethernet reference clock. (LPC1769/68/67/66/64 only).
P1[16]/ ENET_MDC	87	A6	F3	[1]	I/O	**P1[16] —** General purpose digital input/output pin.
					O	**ENET_MDC —** Ethernet MIIM clock (LPC1769/68/67/66/64 only).
P1[17]/ ENET_MDIO	86	B6	F2	[1]	I/O	**P1[17] —** General purpose digital input/output pin.
					I/O	**ENET_MDIO —** Ethernet MIIM data input and output. (LPC1769/68/67/66/64 only).

Table 5. Pin description *…continued*

Symbol	Pin/ball				Type	Description
	LQFP100	TFBGA100	WLCSP100			
VREFN	15	F1	A6		I	**ADC negative reference voltage:** This should be nominally the same voltage as V_{SS} but should be isolated to minimize noise and error. Level on this pin is used as a reference for ADC and DAC.
VBAT	19	G2	A8	[10][12]	I	**RTC pin power supply:** 3.3 V on this pin supplies the power to the RTC peripheral.
n.c.	13	D4, E4	B6, D6		-	not connected.

[1] 5 V tolerant pad providing digital I/O functions with TTL levels and hysteresis. This pin is pulled up to a voltage level of 2.3 V to 2.6 V.

[2] 5 V tolerant pad providing digital I/O functions (with TTL levels and hysteresis) and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant. This pin is pulled up to a voltage level of 2.3 V to 2.6 V.

[3] 5 V tolerant pad providing digital I/O with TTL levels and hysteresis and analog output function. When configured as the DAC output, digital section of the pad is disabled. This pin is pulled up to a voltage level of 2.3 V to 2.6 V.

[4] Open-drain 5 V tolerant digital I/O pad, compatible with I^2C-bus 400 kHz specification. This pad requires an external pull-up to provide output functionality. When power is switched off, this pin connected to the I^2C-bus is floating and does not disturb the I^2C lines. Open-drain configuration applies to all functions on this pin.

[5] Pad provides digital I/O and USB functions. It is designed in accordance with the *USB specification, revision 2.0* (Full-speed and Low-speed mode only). This pad is not 5 V tolerant.

[6] 5 V tolerant pad with 10 ns glitch filter providing digital I/O functions with TTL levels and hysteresis. This pin is pulled up to a voltage level of 2.3 V to 2.6 V.

[7] 5 V tolerant pad with TTL levels and hysteresis. Internal pull-up and pull-down resistors disabled.

[8] 5 V tolerant pad with TTL levels and hysteresis and internal pull-up resistor.

[9] 5 V tolerant pad with 20 ns glitch filter providing digital I/O function with TTL levels and hysteresis.

[10] Pad provides special analog functionality. A 32 kHz crystal oscillator must be used with the RTC.

[11] When the system oscillator is not used, connect XTAL1 and XTAL2 as follows: XTAL1 can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTAL2 should be left floating.

[12] When the RTC is not used, connect VBAT to $V_{DD(REG)(3V3)}$ and leave RTCX1 floating.

8.9.1 Features

- Eight DMA channels. Each channel can support an unidirectional transfer.
- 16 DMA request lines.
- Single DMA and burst DMA request signals. Each peripheral connected to the DMA Controller can assert either a burst DMA request or a single DMA request. The DMA burst size is set by programming the DMA Controller.
- Memory-to-memory, memory-to-peripheral, peripheral-to-memory, and peripheral-to-peripheral transfers are supported.
- Scatter or gather DMA is supported through the use of linked lists. This means that the source and destination areas do not have to occupy contiguous areas of memory.
- Hardware DMA channel priority.
- AHB slave DMA programming interface. The DMA Controller is programmed by writing to the DMA control registers over the AHB slave interface.
- One AHB bus master for transferring data. The interface transfers data when a DMA request goes active.
- 32-bit AHB master bus width.
- Incrementing or non-incrementing addressing for source and destination.
- Programmable DMA burst size. The DMA burst size can be programmed to more efficiently transfer data.
- Internal four-word FIFO per channel.
- Supports 8, 16, and 32-bit wide transactions.
- Big-endian and little-endian support. The DMA Controller defaults to little-endian mode on reset.
- An interrupt to the processor can be generated on a DMA completion or when a DMA error has occurred.
- Raw interrupt status. The DMA error and DMA count raw interrupt status can be read prior to masking.

8.10 Fast general purpose parallel I/O

Device pins that are not connected to a specific peripheral function are controlled by the GPIO registers. Pins may be dynamically configured as inputs or outputs. Separate registers allow setting or clearing any number of outputs simultaneously. The value of the output register may be read back as well as the current state of the port pins.

LPC17xx use accelerated GPIO functions:

- GPIO registers are accessed through the AHB multilayer bus so that the fastest possible I/O timing can be achieved.
- Mask registers allow treating sets of port bits as a group, leaving other bits unchanged.
- All GPIO registers are byte and half-word addressable.
- Entire port value can be written in one instruction.
- Support for Cortex-M3 bit banding.
- Support for use with the GPDMA controller.

Additionally, any pin on Port 0 and Port 2 (total of 42 pins) providing a digital function can be programmed to generate an interrupt on a rising edge, a falling edge, or both. The edge detection is asynchronous, so it may operate when clocks are not present such as during Power-down mode. Each enabled interrupt can be used to wake up the chip from Power-down mode.

8.10.1 Features

- Bit level set and clear registers allow a single instruction to set or clear any number of bits in one port.
- Direction control of individual bits.
- All I/O default to inputs after reset.
- Pull-up/pull-down resistor configuration and open-drain configuration can be programmed through the pin connect block for each GPIO pin.

8.11 Ethernet

Remark: The Ethernet controller is available on parts LPC1769/68/67/66/64. The Ethernet block supports bus clock rates of up to 100 MHz (LPC1768/67/66/64) or 120 MHz (LPC1769). See Table 2.

The Ethernet block contains a full featured 10 Mbit/s or 100 Mbit/s Ethernet MAC designed to provide optimized performance through the use of DMA hardware acceleration. Features include a generous suite of control registers, half or full duplex operation, flow control, control frames, hardware acceleration for transmit retry, receive packet filtering and wake-up on LAN activity. Automatic frame transmission and reception with scatter-gather DMA off-loads many operations from the CPU.

The Ethernet block and the CPU share the Arm Cortex-M3 D-code and system bus through the AHB-multilayer matrix to access the various on-chip SRAM blocks for Ethernet data, control, and status information.

The Ethernet block interfaces between an off-chip Ethernet PHY using the Reduced MII (RMII) protocol and the on-chip Media Independent Interface Management (MIIM) serial bus.

8.11.1 Features

- Ethernet standards support:
  - Supports 10 Mbit/s or 100 Mbit/s PHY devices including 10 Base-T, 100 Base-TX, 100 Base-FX, and 100 Base-T4.
  - Fully compliant with *IEEE standard 802.3*.
  - Fully compliant with 802.3x full duplex flow control and half duplex back pressure.
  - Flexible transmit and receive frame options.
  - Virtual Local Area Network (VLAN) frame support.
- Memory management:
  - Independent transmit and receive buffers memory mapped to shared SRAM.
  - DMA managers with scatter/gather DMA and arrays of frame descriptors.
  - Memory traffic optimized by buffering and pre-fetching.

- Endpoint Maximum packet size selection (up to USB maximum specification) by software at run time.
- Supports SoftConnect and GoodLink features.
- While USB is in the Suspend mode, the part can enter one of the reduced power modes and wake up on USB activity.
- Supports DMA transfers with all on-chip SRAM blocks on all non-control endpoints.
- Allows dynamic switching between CPU-controlled slave and DMA modes.
- Double buffer implementation for Bulk and Isochronous endpoints.

8.12.2 USB host controller

The host controller enables full- and low-speed data exchange with USB devices attached to the bus. It consists of a register interface, a serial interface engine, and a DMA controller. The register interface complies with the OHCI specification.

8.12.2.1 Features

- OHCI compliant.
- One downstream port.
- Supports port power switching.

8.12.3 USB OTG controller

USB OTG is a supplement to the USB 2.0 specification that augments the capability of existing mobile devices and USB peripherals by adding host functionality for connection to USB peripherals.

The OTG Controller integrates the host controller, device controller, and a master-only I^2C-bus interface to implement OTG dual-role device functionality. The dedicated I^2C-bus interface controls an external OTG transceiver.

8.12.3.1 Features

- Fully compliant with *On-The-Go supplement to the USB 2.0 Specification, Revision 1.0a*.
- Hardware support for Host Negotiation Protocol (HNP).
- Includes a programmable timer required for HNP and Session Request Protocol (SRP).
- Supports any OTG transceiver compliant with the *OTG Transceiver Specification (CEA-2011), Rev. 1.0*.

8.13 CAN controller and acceptance filters

Remark: The CAN controllers are available on parts LPC1769/68/66/65/64. See Table 2.

The Controller Area Network (CAN) is a serial communications protocol which efficiently supports distributed real-time control with a very high level of security. Its domain of application ranges from high-speed networks to low cost multiplex wiring.

The CAN block is intended to support multiple CAN buses simultaneously, allowing the device to be used as a gateway, switch, or router among a number of CAN buses in industrial or automotive applications.

- Up to four external outputs corresponding to match registers, with the following capabilities:
  - Set LOW on match.
  - Set HIGH on match.
  - Toggle on match.
  - Do nothing on match.
- Up to two match registers can be used to generate timed DMA requests.

8.22 Pulse width modulator

The PWM is based on the standard Timer block and inherits all of its features, although only the PWM function is pinned out on the LPC17xx. The Timer is designed to count cycles of the system derived clock and optionally switch pins, generate interrupts or perform other actions when specified timer values occur, based on seven match registers. The PWM function is in addition to these features, and is based on match register events.

The ability to separately control rising and falling edge locations allows the PWM to be used for more applications. For instance, multi-phase motor control typically requires three non-overlapping PWM outputs with individual control of all three pulse widths and positions.

Two match registers can be used to provide a single edge controlled PWM output. One match register (PWMMR0) controls the PWM cycle rate, by resetting the count upon match. The other match register controls the PWM edge position. Additional single edge controlled PWM outputs require only one match register each, since the repetition rate is the same for all PWM outputs. Multiple single edge controlled PWM outputs will all have a rising edge at the beginning of each PWM cycle, when an PWMMR0 match occurs.

Three match registers can be used to provide a PWM output with both edges controlled. Again, the PWMMR0 match register controls the PWM cycle rate. The other match registers control the two PWM edge positions. Additional double edge controlled PWM outputs require only two match registers each, since the repetition rate is the same for all PWM outputs.

With double edge controlled PWM outputs, specific match registers control the rising and falling edge of the output. This allows both positive going PWM pulses (when the rising edge occurs prior to the falling edge), and negative going PWM pulses (when the falling edge occurs prior to the rising edge).

8.22.1 Features

- One PWM block with Counter or Timer operation (may use the peripheral clock or one of the capture inputs as the clock source).
- Seven match registers allow up to 6 single edge controlled or 3 double edge controlled PWM outputs, or a mix of both types. The match registers also allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.

8.29.8 Power domains

The LPC17xx provide two independent power domains that allow the bulk of the device to have power removed while maintaining operation of the RTC and the backup Registers.

On the LPC17xx, I/O pads are powered by the 3.3 V ($V_{DD(3V3)}$) pins, while the $V_{DD(REG)(3V3)}$ pin powers the on-chip voltage regulator which in turn provides power to the CPU and most of the peripherals.

Depending on the LPC17xx application, a design can use two power options to manage power consumption.

The first option assumes that power consumption is not a concern and the design ties the $V_{DD(3V3)}$ and $V_{DD(REG)(3V3)}$ pins together. This approach requires only one 3.3 V power supply for both pads, the CPU, and peripherals. While this solution is simple, it does not support powering down the I/O pad ring “on the fly” while keeping the CPU and peripherals alive.

The second option uses two power supplies; a 3.3 V supply for the I/O pads ($V_{DD(3V3)}$) and a dedicated 3.3 V supply for the CPU ($V_{DD(REG)(3V3)}$). Having the on-chip voltage regulator powered independently from the I/O pad ring enables shutting down of the I/O pad power supply “on the fly”, while the CPU and peripherals stay active.

The VBAT pin supplies power only to the RTC domain. The RTC requires a minimum of power to operate, which can be supplied by an external battery. The device core power ($V_{DD(REG)(3V3)}$) is used to operate the RTC whenever $V_{DD(REG)(3V3)}$ is present. Therefore, there is no power drain from the RTC battery when $V_{DD(REG)(3V3)}$ is available.

9. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DD(3V3)}$	supply voltage (3.3 V)	external rail	[2]	−0.5	+4.6	V
$V_{DD(REG)(3V3)}$	regulator supply voltage (3.3 V)		[2]	−0.5	+4.6	V
V_{DDA}	analog 3.3 V pad supply voltage		[2]	−0.5	+4.6	V
$V_{i(VBAT)}$	input voltage on pin VBAT	for the RTC	[2]	−0.5	+4.6	V
$V_{i(VREFP)}$	input voltage on pin VREFP		[2]	−0.5	+4.6	V
V_{IA}	analog input voltage	on ADC related pins	[2][3]	−0.5	+5.1	V
V_I	input voltage	5 V tolerant digital I/O pins; $V_{DD} \geq 2.4$ V	[2][4]	−0.5	+5.5	V_I
		$V_{DD} = 0$ V		−0.5	+3.6	
		5 V tolerant open-drain pins PIO0_27 and PIO0_28	[2][5]	−0.5	+5.5	
I_{DD}	supply current	per supply pin		-	100	mA
I_{SS}	ground current	per ground pin		-	100	mA
I_{latch}	I/O latch-up current	$-(0.5V_{DD(3V3)}) < V_I < (1.5V_{DD(3V3)})$; $T_j < 125$ °C		-	100	mA
T_{stg}	storage temperature		[6]	−65	+150	°C
$T_{j(max)}$	maximum junction temperature				150	°C
$P_{tot(pack)}$	total power dissipation (per package)	based on package heat transfer, not device power consumption		-	1.5	W
V_{ESD}	electrostatic discharge voltage	human body model; all pins	[7]	−4000	+4000	V

[1] The following applies to the limiting values:

a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

b) Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

c) The limiting values are stress ratings only. Operating the part at these values is not recommended, and proper operation is not guaranteed. The conditions for functional operation are specified in Table 8.

[2] Maximum/minimum voltage above the maximum operating voltage (see Table 8) and below ground that can be applied for a short time (< 10 ms) to a device without leading to irrecoverable failure. Failure includes the loss of reliability and shorter lifetime of the device.

[3] See Table 19 for maximum operating voltage.

[4] Including voltage on outputs in 3-state mode.

[5] V_{DD} present or not present. Compliant with the I^2C-bus standard. 5.5 V can be applied to this pin when V_{DD} is powered down.

[6] The maximum non-operating storage temperature is different than the temperature for required shelf life which should be determined based on required shelf lifetime. Please refer to the JEDEC spec (J-STD-033B.1) for further details.

[7] Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

12.3 Internal oscillators

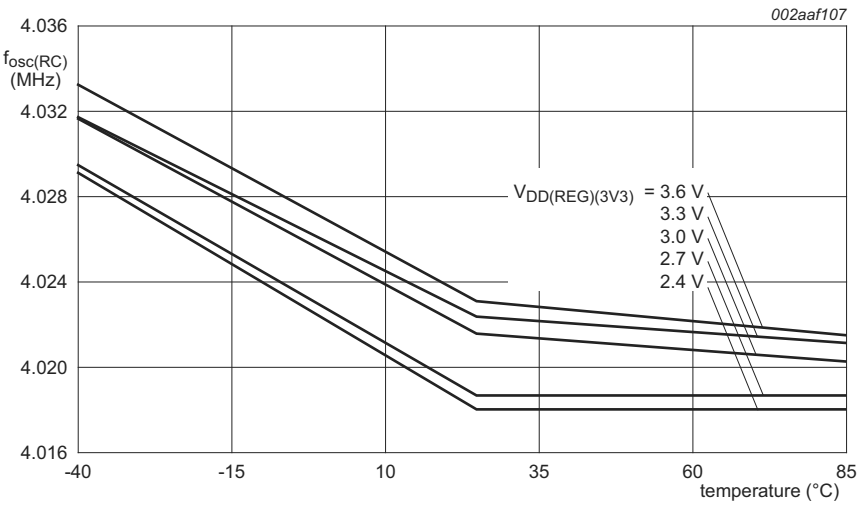
Table 12. Dynamic characteristic: internal oscillators

T_{amb} = −40 °C to +85 °C; 2.7 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V.[1]

Symbol	Parameter	Conditions		Min	Typ[2]	Max	Unit
$f_{osc(RC)}$	internal RC oscillator frequency	-		3.96	4.02	4.04	MHz
$f_{i(RTC)}$	RTC input frequency	-		-	32.768	-	kHz

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.



Conditions: Frequency values are typical values. 4 MHz ± 1 % accuracy is guaranteed for 2.7 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V and T_{amb} = −40 °C to +85 °C. Variations between parts may cause the IRC to fall outside the 4 MHz ± 1 % accuracy specification for voltages below 2.7 V.

Fig 17. Internal RC oscillator frequency versus temperature

12.4 I/O pins

Table 13. Dynamic characteristic: I/O pins[1]

T_{amb} = −40 °C to +85 °C; $V_{DD(3V3)}$ over specified ranges.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
t_r	rise time	pin configured as output		3.0	-	5.0	ns
t_f	fall time	pin configured as output		2.5	-	5.0	ns

[1] Applies to standard I/O pins.

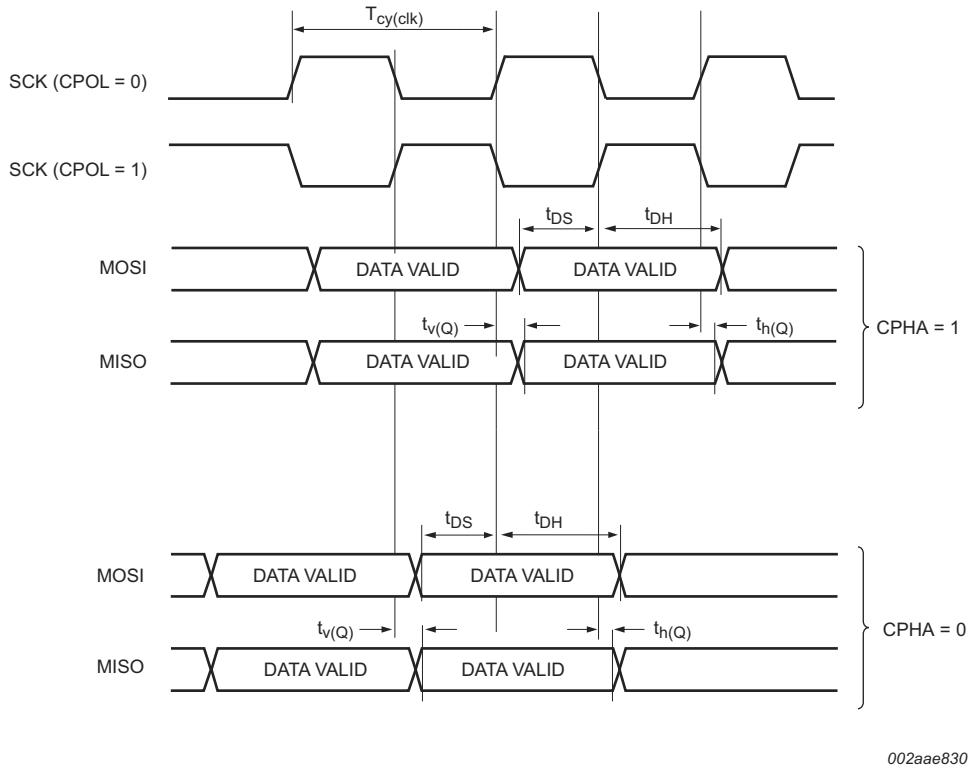


Fig 22. SSP slave timing in SPI mode

Table 20. ADC characteristics (lower resolution)

T_{amb} = −40 °C to +85 °C unless otherwise specified; 12-bit ADC used as 10-bit resolution ADC.[1]

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
E_D	differential linearity error		[2][3]	-	±1	-	LSB
$E_{L(adj)}$	integral non-linearity		[4]	-	±1.5	-	LSB
E_O	offset error		[5]	-	±2	-	LSB
E_G	gain error		[6]	-	±2	-	LSB
$f_{clk(ADC)}$	ADC clock frequency	$3.0\ V \leq V_{DDA} \leq 3.6\ V$		-	-	33	MHz
		$2.7\ V \leq V_{DDA} < 3.0\ V$		-	-	25	MHz
$f_{c(ADC)}$	ADC conversion frequency	$3\ V \leq V_{DDA} \leq 3.6\ V$	[7]	-	-	500	kHz
		$2.7\ V \leq V_{DDA} < 3.0\ V$	[7]	-	-	400	kHz

[1] V_{DDA} and VREFP should be tied to $V_{DD(3V3)}$ if the ADC and DAC are not used.

[2] The ADC is monotonic, there are no missing codes.

[3] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 28.

[4] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See Figure 28.

[5] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See Figure 28.

[6] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 28.

[7] The conversion frequency corresponds to the number of samples per second.

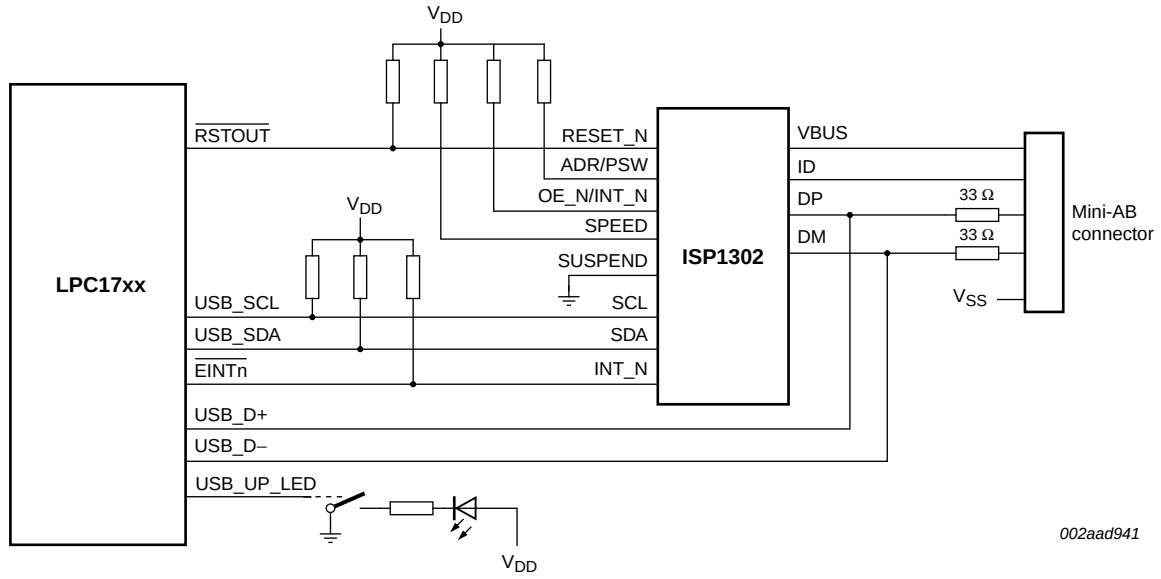


Fig 33. USB OTG port configuration

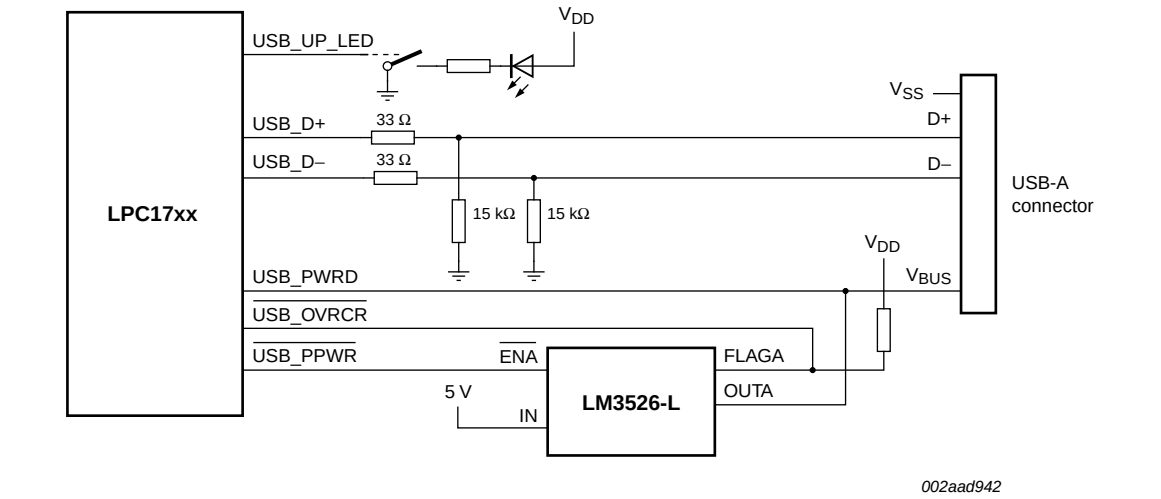


Fig 34. USB host port configuration

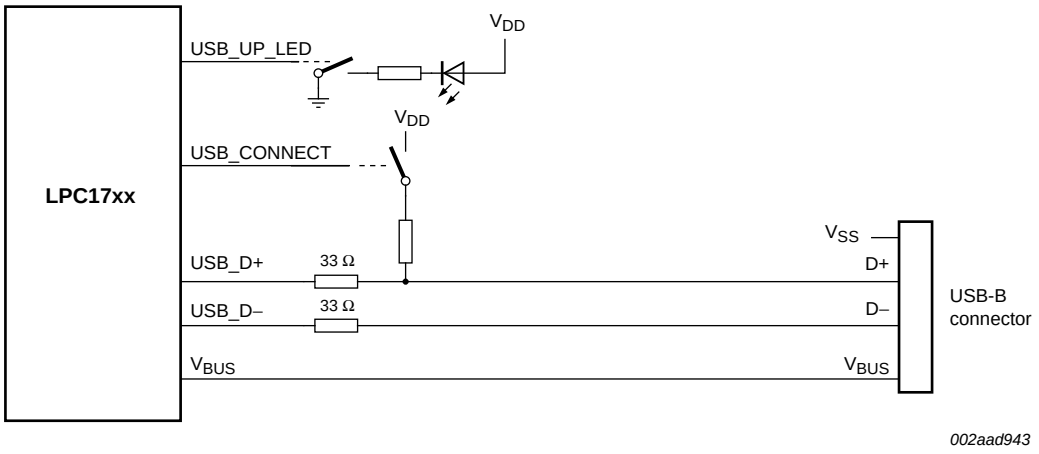


Fig 35. USB device port configuration

15.2 Crystal oscillator XTAL input and component selection

The input voltage to the on-chip oscillators is limited to 1.8 V. If the oscillator is driven by a clock in slave mode, it is recommended that the input be coupled through a capacitor with C_i = 100 pF. To limit the input voltage to the specified range, choose an additional capacitor to ground C_g which attenuates the input voltage by a factor $C_i/(C_i + C_g)$. In slave mode, a minimum of 200 mV(RMS) is needed.

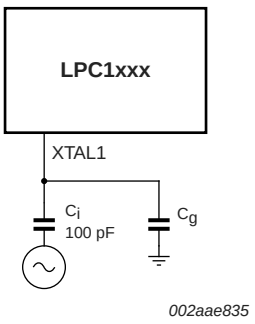


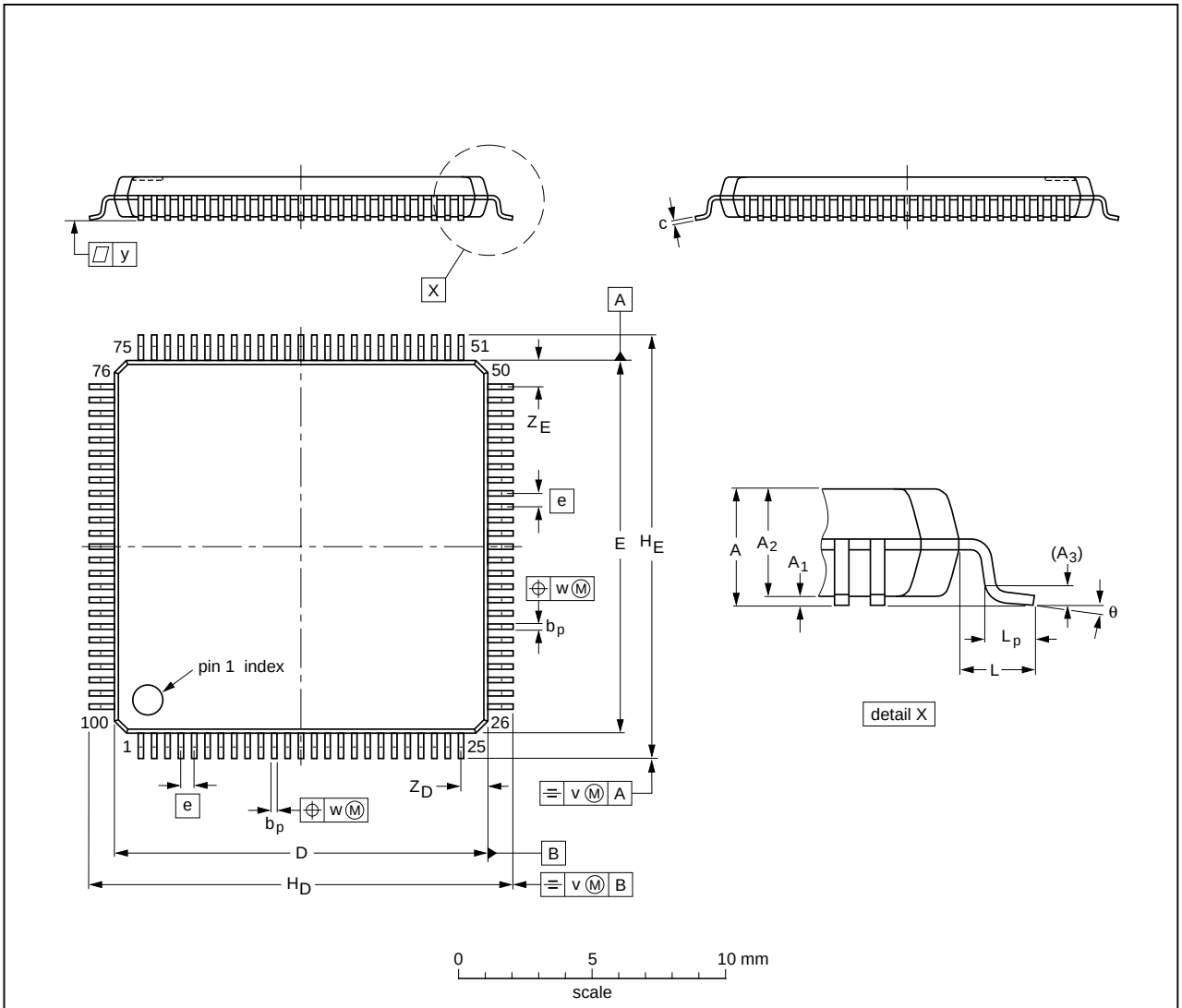
Fig 36. Slave mode operation of the on-chip oscillator

In slave mode the input clock signal should be coupled by means of a capacitor of 100 pF (Figure 36), with an amplitude between 200 mV(RMS) and 1000 mV(RMS). This corresponds to a square wave signal with a signal swing of between 280 mV and 1.4 V. The XTALOUT pin in this configuration can be left unconnected.

External components and models used in oscillation mode are shown in Figure 37 and in Table 23 and Table 24. Since the feedback resistance is integrated on chip, only a crystal and the capacitances C_{X1} and C_{X2} need to be connected externally in case of fundamental mode oscillation (the fundamental frequency is represented by L, C_L and R_S). Capacitance C_P in Figure 37 represents the parallel package capacitance and should not be larger than 7 pF. Parameters F_{OSC}, C_L, R_S and C_P are supplied by the crystal manufacturer.

16. Package outline

LQFP100: plastic low profile quad flat package; 100 leads; body 14 x 14 x 1.4 mm **SOT407-1**



DIMENSIONS (mm are the original dimensions)

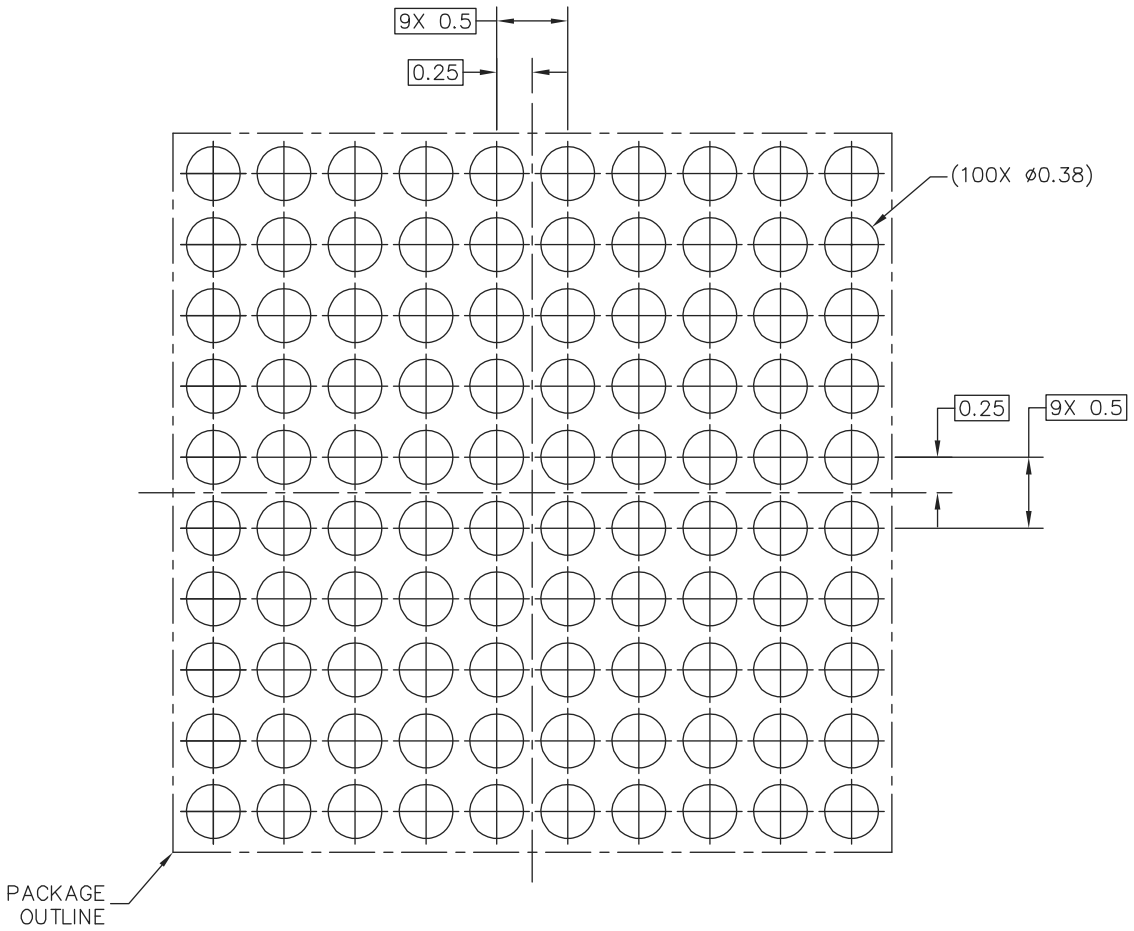
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.27 0.17	0.20 0.09	14.1 13.9	14.1 13.9	0.5	16.25 15.75	16.25 15.75	1	0.75 0.45	0.2	0.08	0.08	1.15 0.85	1.15 0.85	7^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT407-1	136E20	MS-026				~~00-02-01~~ 03-02-20

Fig 40. Package outline SOT407-1 (LQFP100)



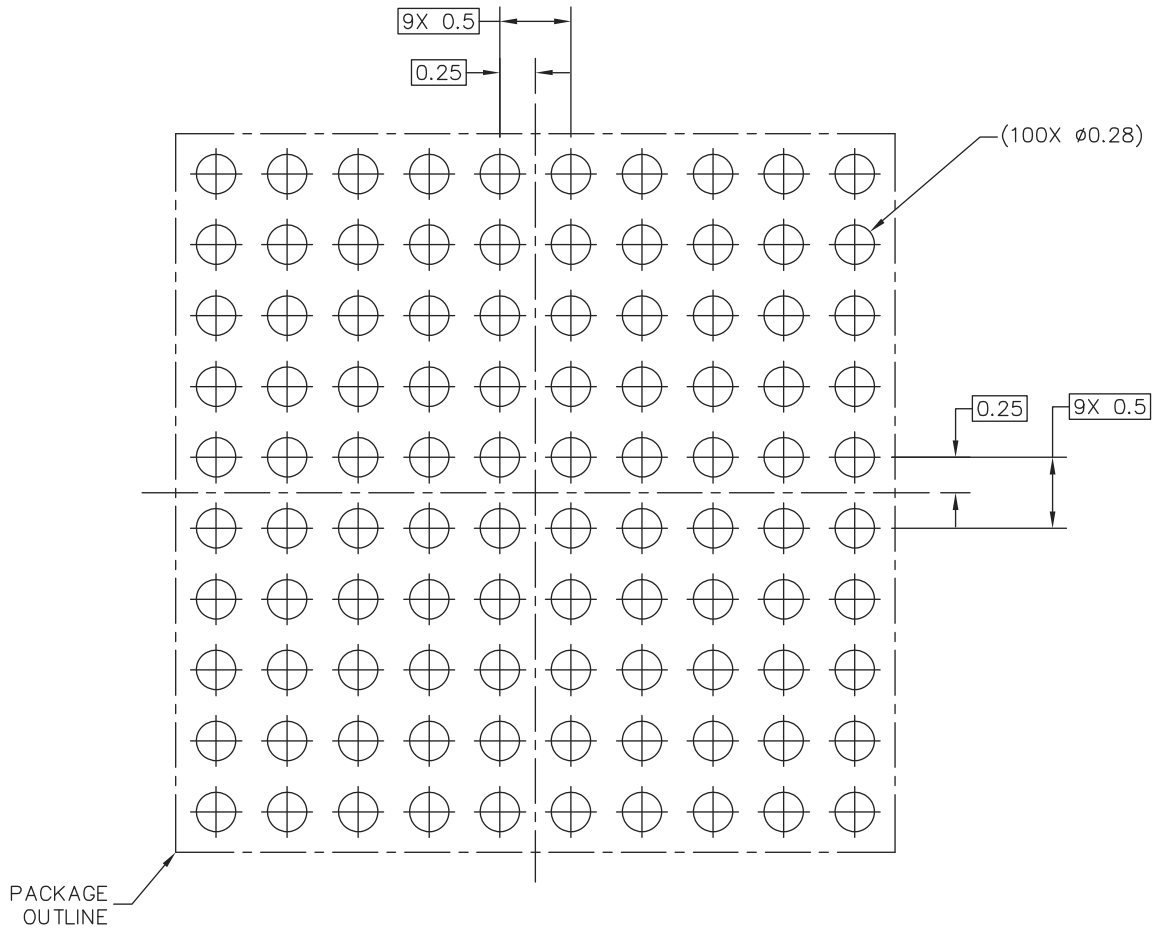
PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 06 MAR 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1450–2	REVISION: 0	

Fig 45. Reflow soldering of the WLCSP100 package (part 1)



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 DATE: 06 MAR 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1450-2	REVISION: 0	

Fig 46. Reflow soldering of the WLCSP100 package (part 2)

20. Revision history

Table 27. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
LPC1769_68_67_66_65_64_63 v.9.8	20180504	Product data sheet	-	LPC1769_68_67_66_65_64 v.9.7
Modifications:	• Added Figure 45 “Reflow soldering of the WLCSP100 package (part 1)”, Figure 46 “Reflow soldering of the WLCSP100 package (part 2)”, and Figure 47 “Reflow soldering of the WLCSP100 package (part 3)”.			
LPC1769_68_67_66_65_64_63 v.9.7	20170501	Product data sheet	-	LPC1769_68_67_66_65_64 v.9.6
Modifications:	• Updated Table 2 “Ordering options”: WLCSP100 with body size 100 balls, 5.07 x 5.07 x 0.53mm; was 5.074 x 5.074 x 0.6mm. • Updated Figure 42 “Package outline SOT1450-2 LPC1768UK (WLCSP100)”.			
LPC1769_68_67_66_65_64_63 v.9.6	20150818	Product data sheet	-	LPC1769_68_67_66_65_64 v.9.5
Modifications:	• Changed max value of $t_{v(Q)}$ (data output valid time) in SPI mode to $3*T_{cy(PCLK)}$ + 2.5 ns. See Table 16 “Dynamic characteristics: SSP pins in SPI mode”. • Updated Section 2 “Features and benefits”: Added Boundary scan Description Language (BSDL) is not available for this device. • Updated Figure 5 “LPC17xx memory map”: APB0 slot 7 (0x4001C000) was "reserved" and changed it to I2C0. • Changed pins for $V_{DD(REG)(3V3)}$ from F4 and F0 to F4 and F10. See Table 5 “Pin description”. • Removed footnote 1: “5 V tolerant pad providing digital I/O functions with TTL levels and hysteresis. This pin is pulled up to a voltage level of 2.3 V to 2.6 V” from TDO/SWO, TCK/SWDCLK, and RTCK, pins. See Table 5 “Pin description”. • Added a column for GPIO pins and device order part number to the ordering options table. See Table 2 “Ordering options”.			
LPC1769_68_67_66_65_64_63 v.9.5	<tbd>	Product data sheet	-	LPC1769_68_67_66_65_64 v.9.4
Modifications:	• SSP timing diagram updated. SSP timing parameters $t_{v(Q)}$, $t_{h(Q)}$, t_{DS}, and t_{DH} added. See Section 12.7 “SSP interface”. • Parameter $T_{j(max)}$ added in Table 6 “Limiting values”. • SSP maximum bit rate in master mode corrected to 33 Mbit/s.			
LPC1769_68_67_66_65_64_63 v.9.4	20140404	Product data sheet	-	LPC1769_68_67_66_65_64 v.9.3
Modifications:	• Added LPC1768UK. • Table 5 “Pin description”: Changed RX_MCLK and TX_MCLK type from INPUT to OUTPUT.			
LPC1769_68_67_66_65_64_63 v.9.3	20140108	Product data sheet	-	LPC1769_68_67_66_65_64 v.9.2
Modifications:	• Table 7 “Thermal resistance (±15 %)”: – Added TFBGA100. – Added ±15 % to table title.			